



## Automotive power Schottky rectifier

Datasheet - production data

#### **Features**

- Negligible switching losses
- Low forward voltage drop for higher efficiency
- Low thermal resistance
- Avalanche capability specified
- AEC-Q101 qualified
- ECOPACK®2 compliant component

### **Description**

Power Schottky rectifier suited for switch mode power supplies and high frequency inverters.

This device is intended for use in low voltage output for small battery chargers and battery protection in automotive applications.

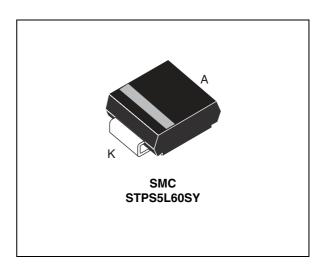


Table 1. Device summary

I <sub>F(AV)</sub>	5 A
V <sub>RRM</sub>	60 V
T <sub>j (max)</sub>	150 °C
V <sub>F (max)</sub>	0.53 V

**Characteristics** STPS5L60-Y

#### **Characteristics** 1

Table 2. Absolute ratings (limiting values)

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage			60	V
I <sub>F(RMS)</sub>	Forward rms current		15	Α	
I <sub>F(AV)</sub>	Average forward current	Average forward current $T_I = 100  ^{\circ}\text{C}  \delta = 0.5$		5	Α
I <sub>FSM</sub>	Surge non repetitive forward current	Half wave, single phase $t_p = 10 \text{ ms}$		150	Α
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 1 μs T <sub>j</sub> = 25 °C		4000	W
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
T <sub>j</sub>	Operating junction temperature <sup>(1)</sup>			-40 to +150	°C
dV/dt	Critical rate of rise of reverse voltage (rated V <sub>R</sub> , T <sub>j</sub> = 25 °C)			10000	V/µs

 $<sup>\</sup>frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit
R <sub>th (j-l)</sub>	Junction to leads	15	°C/W

Static electrical characteristics Table 4.

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
		T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$			0.22	mA
I <sub>R</sub> <sup>(1)</sup>	(1) Reverse leakage current	T <sub>j</sub> = 100 °C			10	25	
		T <sub>j</sub> = 125 °C			40	100	
	V <sub>F</sub> <sup>(1)</sup> Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A		0.47	0.52	
V <sub>F</sub> <sup>(1)</sup> Fo		T <sub>j</sub> = 100 °C			0.43	0.49	V
		T <sub>j</sub> = 125 °C			0.42	0.48	

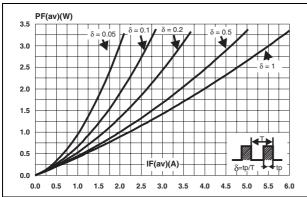
<sup>1.</sup> Pulse test: tp = 380  $\mu$ s,  $\delta$  < 2%

To evaluate the conduction losses use the following equation: P = 0.39 x  $I_{F(AV)}$  + 0.028x  $I_{F}^2$  (RMS)

$$P = 0.39 \text{ x } I_{F(AV)} + 0.028 \text{x } I_{F^2(BMS)}$$

STPS5L60-Y Characteristics

Figure 1. Conduction losses versus average Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5)



F(av)(A)

6

Rin(j-a)=Rin(j-1)

4

3

SMC
Rin(j-a)=60°C/W

1

8=tp/T tp

Tamb(°C)

0

25

50

75

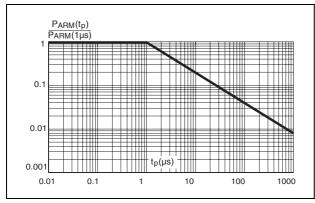
100

125

150

Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature



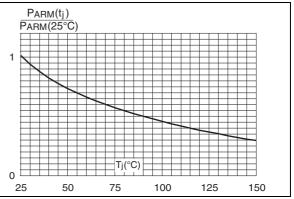
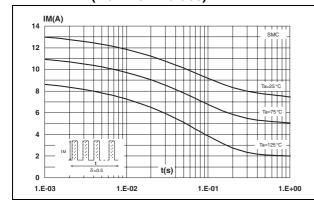
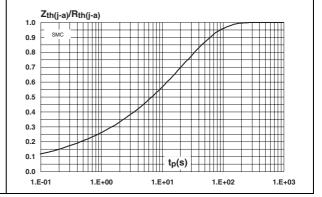


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration

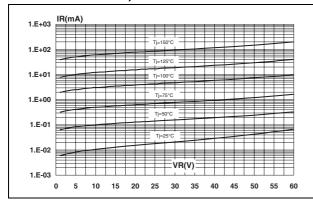




Characteristics STPS5L60-Y

Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

Figure 8. Junction capacitance versus reverse voltage applied (typical values)

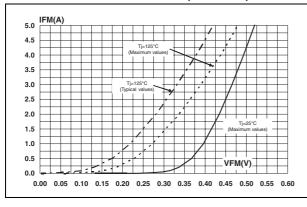


1000 C(pF)

| F=1M+tz | Voice-30mV | T|=25°C | VR(V) | 100

Figure 9. Forward voltage drop versus forward current (low level)

Figure 10. Forward voltage drop versus forward current (high level)



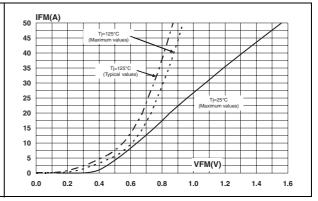
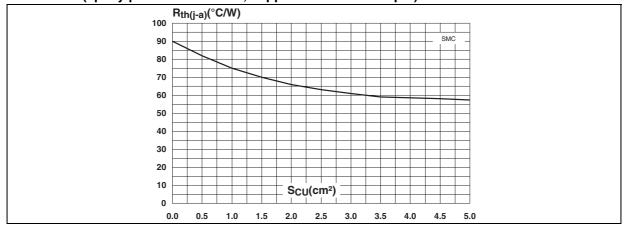


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed board FR4, copper thickness =  $35 \mu m$ )



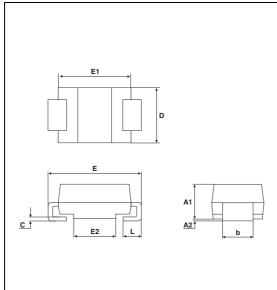
STPS5L60-Y Package information

### 2 Package information

- Epoxy meets UL94, V0
- Lead-free package

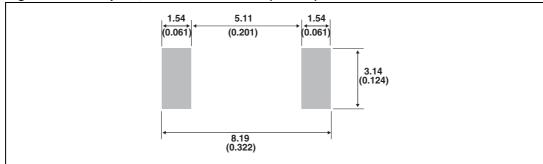
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 5. SMC dimensions



	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
A1	1.90	2.45	0.075	0.096	
A2	0.05	0.20	0.002	0.008	
b <sup>(1)</sup>	2.90	3.20	0.114	0.126	
c <sup>(1)</sup>	0.15	0.40	0.006	0.016	
D	5.55	6.25	0.218	0.246	
Е	7.75	8.15	0.305	0.321	
E1	6.60	7.15	0.260	0.281	
E2	4.40	4.70	0.173	0.185	
L	0.75	1.50	0.030	0.059	

Figure 12. Footprint, dimensions in mm (inches)



<sup>1.</sup> Dimensions b and c apply to plated leads

Ordering information STPS5L60-Y

# **3** Ordering information

 Table 6.
 Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS5L60SY	S56Y	SMC	0.245 g	2500	Tape and reel

## 4 Revision history

Table 7. Document revision history

Date	Revision	Description of Changes
29-Mar-2012	1	Initial issue

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